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(54) **Title:** CARTRIDGE WITH LAMINATED MANIFOLD

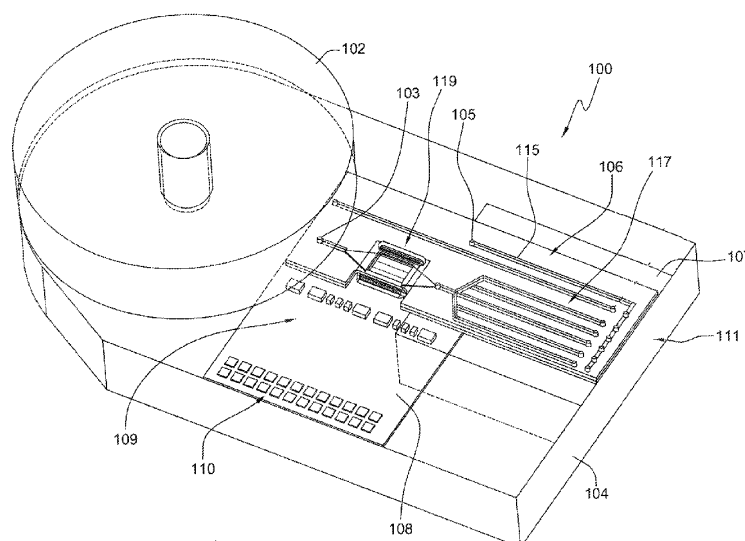


FIG. 1

(57) **Abstract:** A circuit with electrical interconnect for external electronic connection and sensor (s) on a die are combined with a laminated manifold to deliver a liquid reagent over an active surface of the sensor (s). The laminated manifold includes fluidic channel (s), an interface between the die and the fluidic channel (s) being sealed. Also disclosed is a method, the method including assembling a laminated manifold including fluidic channel (s), attaching sensor (s) on a die to a circuit, the circuit including an electrical interconnect, and attaching a planarization layer to the circuit, the planarization layer including a cut out for the die. The method further includes placing sealing adhesive at sides of the die, attaching the laminated manifold to the circuit, and sealing an interface between the die and fluidic channel (s).

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